

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6)	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	4.2 3.4	А
Pulsed Drain Current (Note 7)			I _{DM}	27	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Power Dissipation (Note 6)	$T_A = +25$ °C $T_A = +70$ °C	υ_	0.8 0.5	W
Thermal Resistance, Junction to Ambient @T _A = +25°C		$R_{ heta JA}$	156	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Notes:

- 6. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 7. Repetitive rating, pulse width limited by junction temperature.

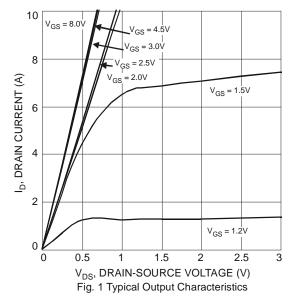
Electrical Characteristics (@TA = +25°C unless otherwise specified.)

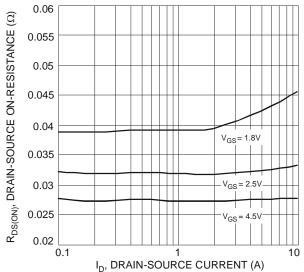
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	_	±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(th)}	0.4	_	1.0	V	$V_{DS} = V_{GS}$, $I_D = 50\mu A$	
Static Drain-Source On-Resistance	0	-	-	90 120	mΩ	$V_{GS} = 4.5V, I_D = 3.6A$	
Static Dialit-Source Off-Nesistance	R _{DS} (ON)					$V_{GS} = 2.5V, I_D = 3.1A$	
Forward Transfer Admittance	Y _{fs}	_	13	_	S	$V_{DS} = 5V, I_{D} = 3.6A$	
Diode Forward Voltage	V_{SD}	_	0.75	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{iss}	-	594.3	_	pF		
Output Capacitance	Coss	-	64.5	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C_{rss}	_	57.7	_	pF		
Gate Resistance	R_g	_	1.5	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	7.0	_	nC	$V_{GS} = 4.5V$, $V_{DS} = 10V$, $I_{D} = 3.6A$	
Gate-Source Charge	Q_{gs}	_	0.9	_	nC		
Gate-Drain Charge	Q_{gd}	_	1.4	_	nC		
Turn-On Delay Time	t _{D(on)}	_	7.4	_	ns		
Turn-On Rise Time	t _r	-	9.8	_	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	t _{D(off)}	-	28.1	_	ns	$R_L = 2.78\Omega, R_G = 1.0\Omega$	
Turn-Off Fall Time	t _f	_	6.7	_	ns		

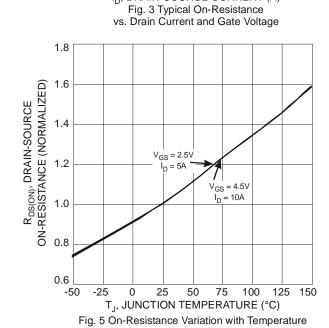
Notes:

- 8. Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to production testing.









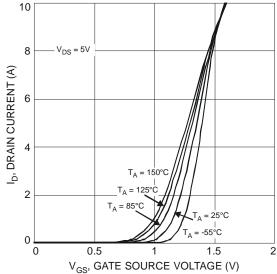


Fig. 2 Typical Transfer Characteristics

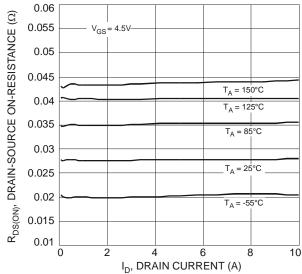


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

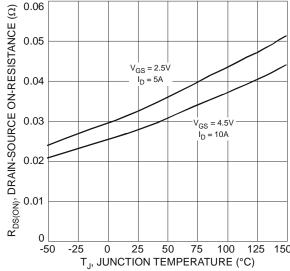


Fig. 6 On-Resistance Variation with Temperature



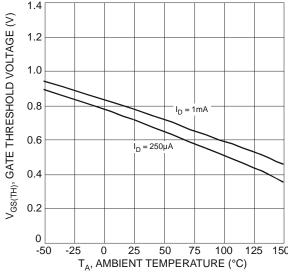
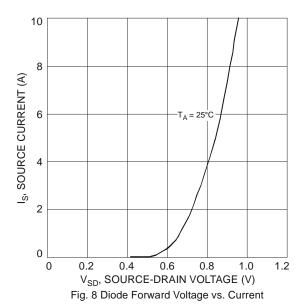
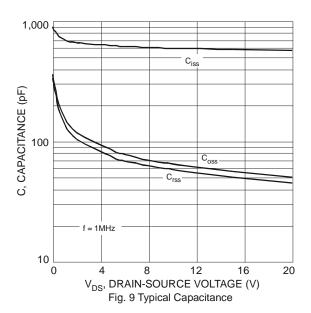
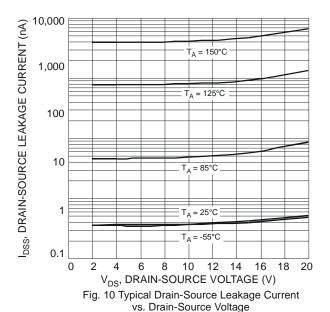


Fig. 7 Gate Threshold Variation vs. Ambient Temperature







Duty Cycle, $D = t_1/t_2$

100

1,000

10

D = 0.7 r(t), TRANSIENT THERMAL RESISTANCE D = 0.5 0.1 D = 0.1 $R_{\theta JA}(t) = r(t) * R_{\theta JA}$ $R_{\theta JA} = 157^{\circ}C/W$ 0.01 $T_J - T_A = P * R_{\theta JA}(t)$

t₁, PULSE DURATION TIME (s)

0.1

0.001 0.00001

0.0001

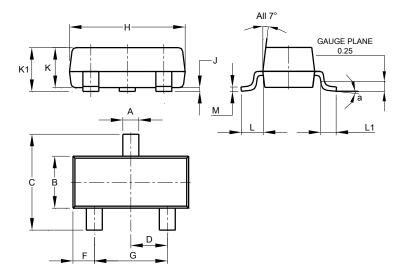
0.001

0.01



Package Outline Dimensions

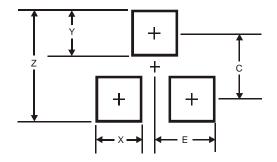
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT23					
Dim	Min	Max	Тур		
Α	0.37	0.51	0.40		
В	1.20	1.40	1.30		
C	2.30	2.50	2.40		
D	0.89	1.03	0.915		
F	0.45	0.60	0.535		
G	1.78	2.05	1.83		
Н	2.80	3.00	2.90		
J	0.013	0.10	0.05		
K	0.890	1.00	0.975		
K1	0.903	1.10	1.025		
L	0.45	0.61	0.55		
L1	0.25	0.55	0.40		
М	0.085	0.150	0.110		
α	8°				
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Υ	0.9
С	2.0
E	1.35



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